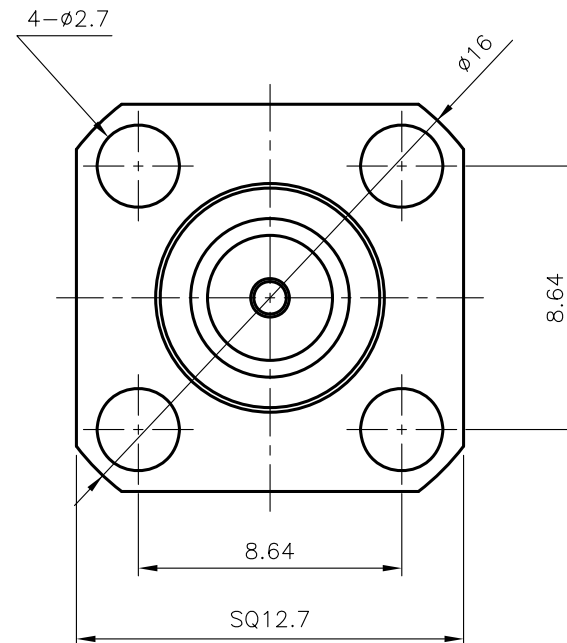
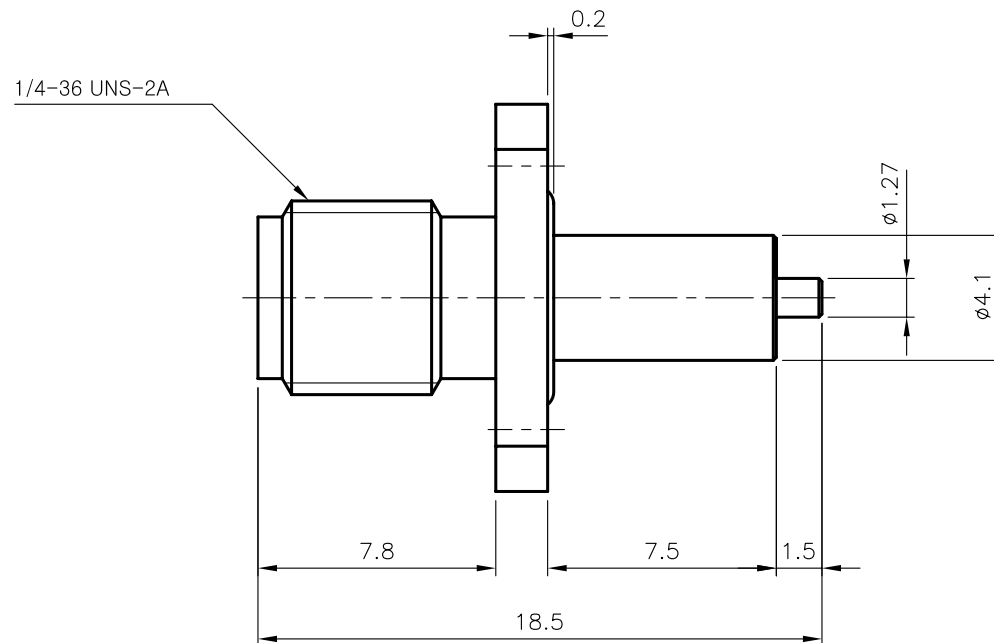


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.M.LEE	I.C.KIM	2014.11.17.
1	[설번 No.201905-0005] 고객사요청 (핀 도금두께 변경 및 가스켓 사이즈 변경)	S.Y.EUN	I.C.KIM	2019.05.31.



4	INSULATOR	1	TEFLON		DIN00097-N/1
3	GASKET	1	SILICONE RUB		DGK00237-N/1 DGK00020-N/1
2	CONTACT	1	BeCu C17300	Gold (1.27μm) Gold Plate	DCT03290-5/1
1	BODY	1	SUS303	Passivate	DBD03763-5/2 DBD03774-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2019. 05. 31.			 KJ COMTECH CO.,LTD. RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM		
	±1°	CHECKED BY			
MATERIAL		DRAWN BY		TITLE	
-		S.Y.EUN		SMA50 SOLDER END JS-4H	
FINISH	-	SCALE	UNIT		A4
		4/1	mm		
		DWG NO. CN03335-7/1			
		REVISION 1		SHEET 1 of 1	